



BW16 Specification

Version V1.2.2

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Document resume

Version	Date	Develop/revise content	Edition	Approve
V0.9	2019.06.15	Initial release	Yang Xiaofei	Hong Xu
V1.0	2019.10.29	Updated	Xie Yiji	Hong Xu
V1.1	2021.02.05	Updated flash	Xie Yiji	Hong Xu
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1. Product Overview

BW16 is a dual-frequency Wi-Fi Bluetooth SoC module based on RTL8720DN. BW16 supports dual-frequency (2.4ghz or 5ghz) WLAN and low-power Bluetooth 5.0; it integrates ARM V8 (compatible with Cortex-M4F) high-performance MCU,ARM V8M (compatible with Cortex-M0) low-power MCU,WLAN(802.11 a / b / g / n), MAC, Bluetooth baseband and RF baseband) and provides a set of configurable GPIO ports for the control of different peripherals.

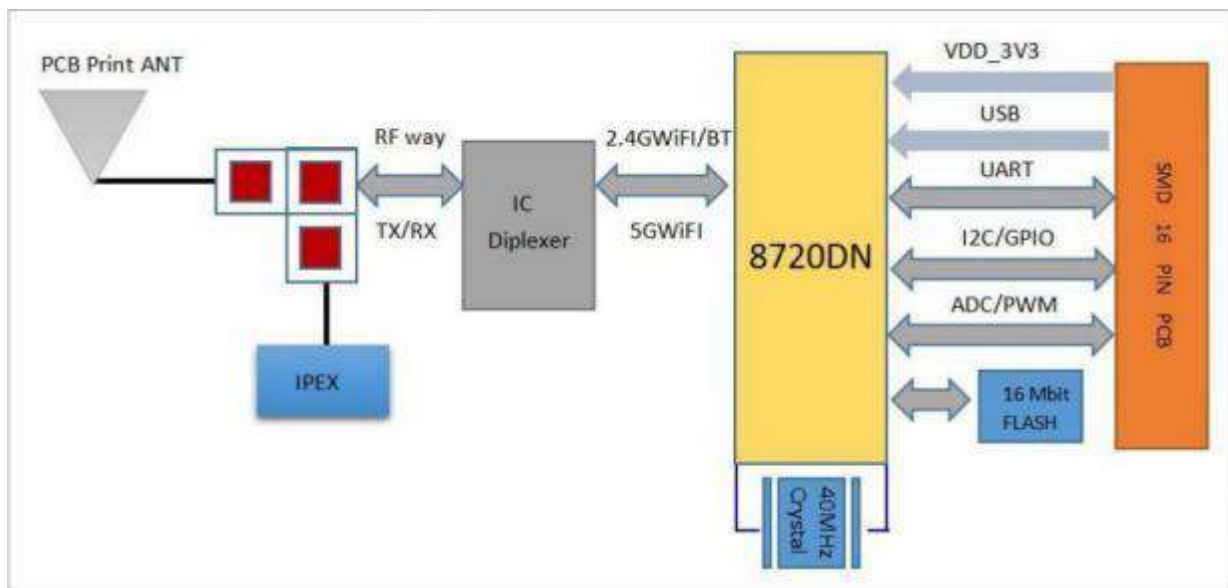


Figure 1 Main chip architecture diagram

1.1. Features

- Support for either 802.11a/b/g/n, 2.4GHz or 5GHz
- Supports the HT 20 / HT 40 mode
- Supports low power beacon listening mode, low power receiving mode and low power hanging mode
- Built-in AES / DES / SHA hardware engine
- Support TrustZone-M and support safe startup
- Supports the SWD debug port access protection and disabled modes
- Support for BLE 5.0
- Bluetooth supports high-power mode (7 dBm, sharing the same PA with Wi-Fi)
- Wi-Fi and Bluetooth share the same antenna
- Support the STA / AP / STA + AP mode and confounding mode
- Support for Android, iOS Simple Config (App) Wi-Fi one-click distribution network
- Support for Bluetooth auxiliary distribution network
- Support for serial port local upgrade and remote firmware upgrade (FOTA)
- Support secondary development, support programming in Linux and Windows environments
- Support for Arduino development

2. Main Parameters

Table 1 Main Parameter

Model	BW16
Package	SMD-16
Dimension	24*16*3(±0.2)MM
Antenna	On-Board PCB Antenna / I-PEX
Frequency	2400~2483.5MHz & 5180~5825MHz
Operating Temperature	-40 °C~85 °C
Store Temperature	-40 °C~125 °C, <90%RH
Power Supply Voltage	3.0V~3.6V, I>500mA
Interface	UART/GPIO/ADC/PWM/IIC/SPI/IR/SWD/USB
Available GPIO	13
UART Baudrates	110~ 6000000 bps, Default 115200bps
Bluetooth	BLE 5.0 without BR/EDR
Wireless Security	WAPI, WEP, WPA/WPA2/WPA3-PSK, WPA/WPA2/WPA3-EAP
SPI Flash	Default 4MB (Optional 2MB, 8MB, 16MB)

2.1. Electrical parameter

BW16 module is an electrostatic sensitive device, which needs special ES precautions. When used ESD protective devices should be added. The correct ESD processing and packaging must be adopted in the transportation, operation and use of BW16 modules. Do not touch the module by hand or weld with a non-antistatic soldering iron to avoid damage to the module.



Figure 2 ESD Warning Logo

2.2. Electrical parameter

Table 2 Electric Characteristic

Parameter	Min	Typical	Max	Unit
DC 3.3V (with internal regulator and integration CMOS PA)	3.0	3.3	3.6	V
Figure I/O supply voltage	1.76	1.8~3.3	3.3	V
DC_IO_33 (3.3V I/O rated current)	-	-	50	mA
Electrostatic protection (VESD)	-	-	2000	V

2.3. Wi-Fi Radio Performance

Table 3 Wi-Fi Radio Performance

Description	Typical			Unit
Operating Frequency	2400~2483.5 and 5180~5825			MHz
Output Power				
Mode	Min	Typical	Max	Unit
11a mode, PA output power	12	14	16	dBm
11n mode, PA output power	12	14	16	dBm
11g mode, PA output power	13	15	17	dBm
11b mode, PA output power	14	16	18	dBm
Rx Sensitivity				
Mode	Min	Typical	Max	Unit
CCK, 1Mbps	-	≤-90	-	dBm
CCK, 11Mbps	-	≤-85	-	dBm
6Mbps (1/2 BPSK)	-	≤-88	-	dBm
54Mbps (3/4 64-QAM)	-	≤-70	-	dBm
HT20 (MCS7)	-	≤-67	-	dBm

2.4. BLE Radio Performance

表 4 BLE Radio Performance

Description	Typical			Unit
Operating Frequency	2400 ~ 2483.5MHz			MHz
Output Power				
Mode	Min	Typical	Max	Unit
1Mbps	5	7	9	dBm
2Mbps	5	7	9	dBm
Rx Sensitivity				
Mode	Min	Typical	Max	Unit
1Mbps @30.8%PER	-	-92	-	dBm
2Mbps @30.8%PER	-	-92	-	dBm

3. Appearance & Package

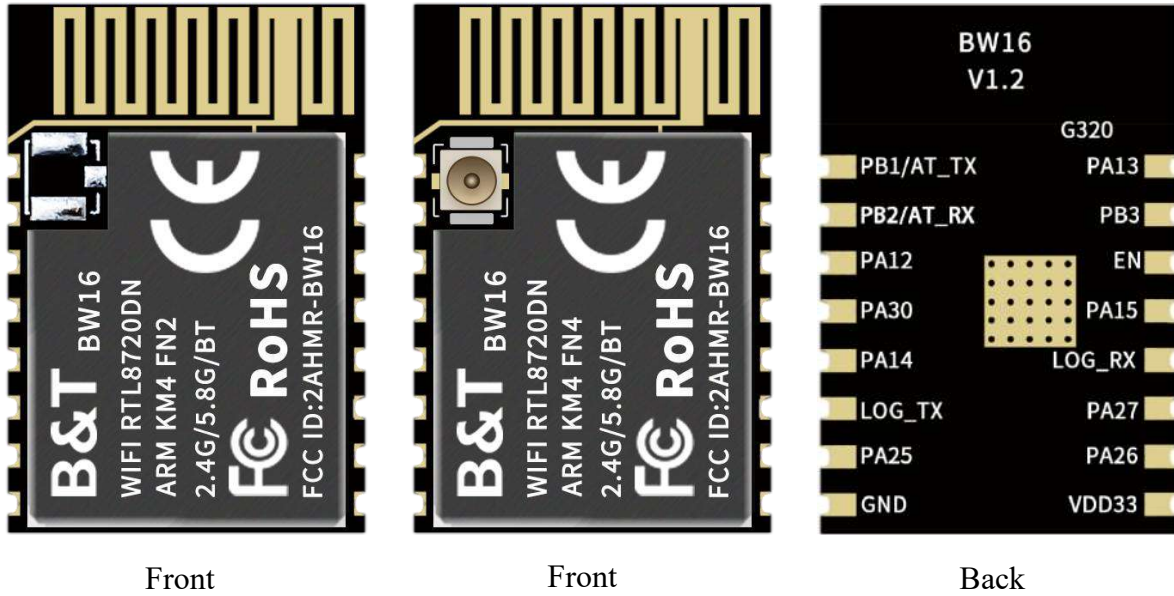


Figure 3 Appearance

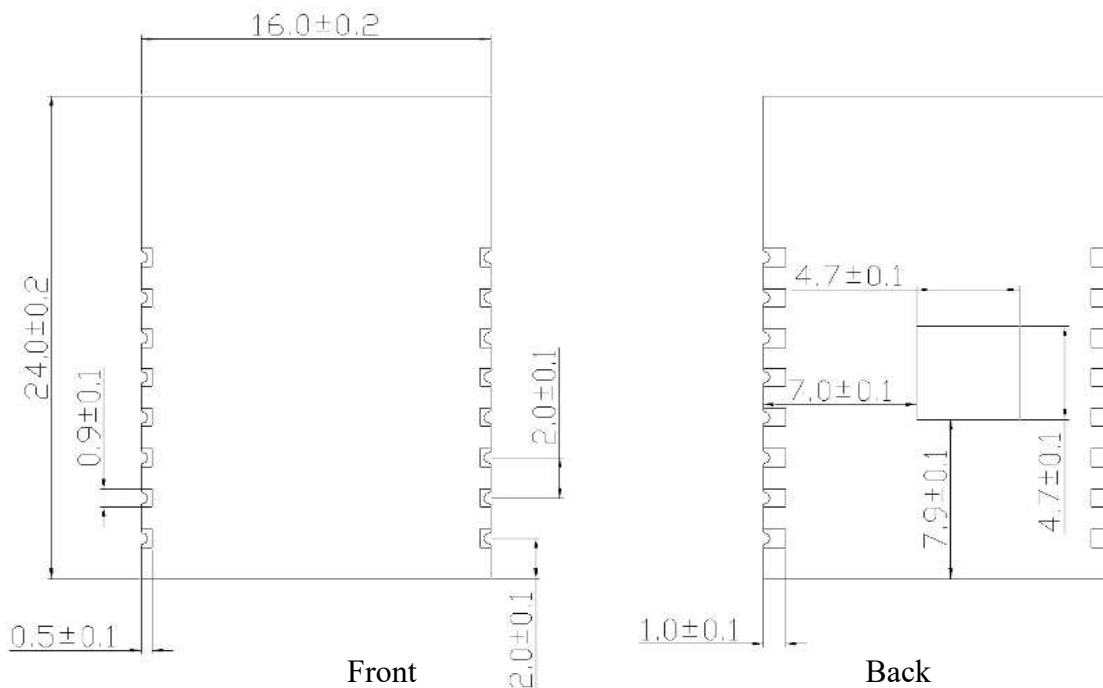


Figure 4 Package

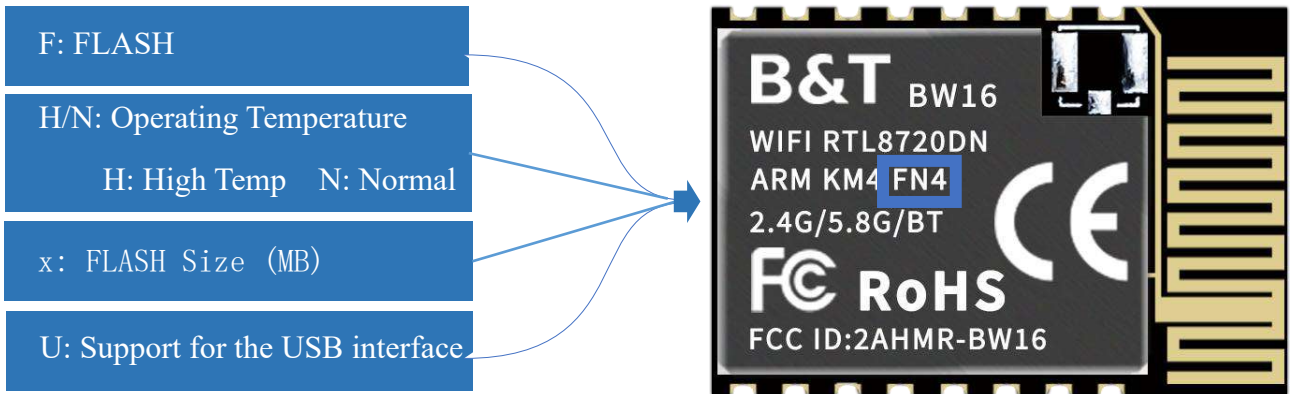


Figure 5 Order Information 支持 USB 接口

4. Pin Definitions

BW16 has 16 interface, refer to following Pin diagram , Table 2.2 is definition of interfaces.

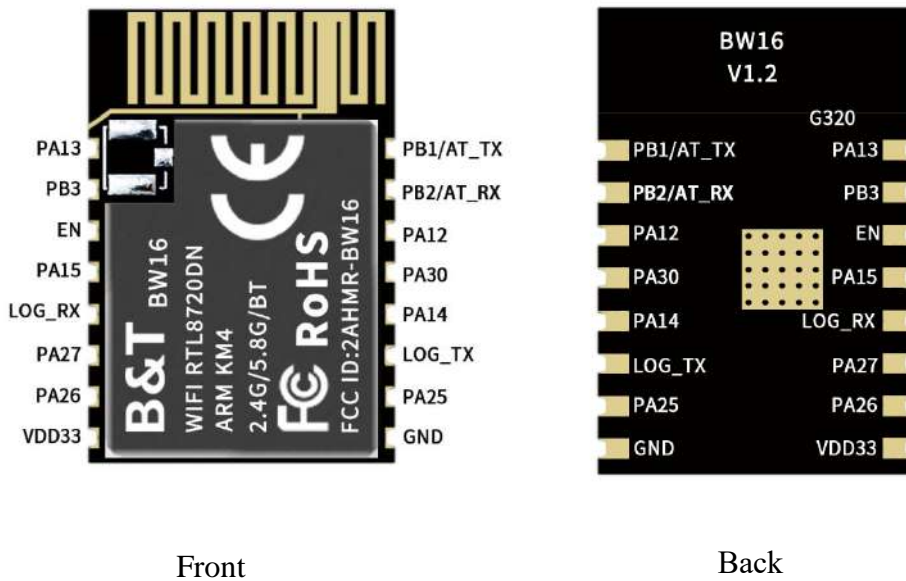


Figure 6 Pin out Diagram

Table 5 Pin definitions

No	Name	Description
1	PA13	LP_PWM1/SPI1_MISO
2	PB3	ADC/SWD_CLK
3	CHIP_EN	Chip Enabled
4	PA15	SPI1_CS
5	PA8	UART_LOG_RXD
6	PA27	SWD_DATA
7	PA26	LP_I2C_SDA/LP_PWM5
8	VDD_3V3	3.3V (VDD)
9	GND	Ground
10	PA25	LP_I2C_SCL/LP_PWM4/HSDM
11	PA7	UART_LOG_TXD
12	PA14	SPI1_CLK
13	PA30	LP_PWM1
14	PA12	SPI1_MOSI/LP_PWM0
15	PB2	LP_UART_RXD
16	PB1	LP_UART_TXD

Note: 1. When the LOG _ TX moment is low, the module enters the burning mode; When the moment is high, the module starts normally and the internal pull up by default.

5. Schematic

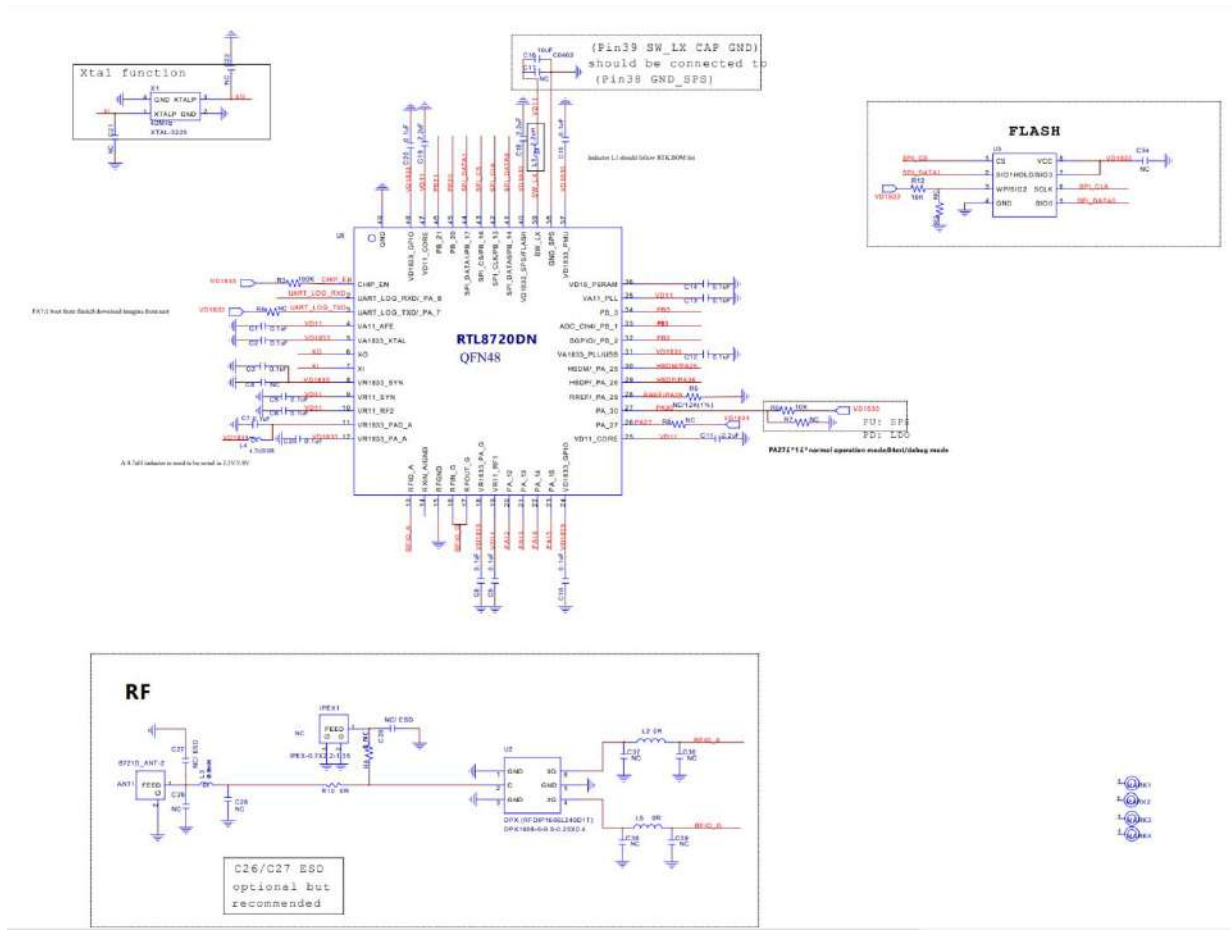


Figure7 Schematic

6. Design Guideline

6.1. Application Circuit

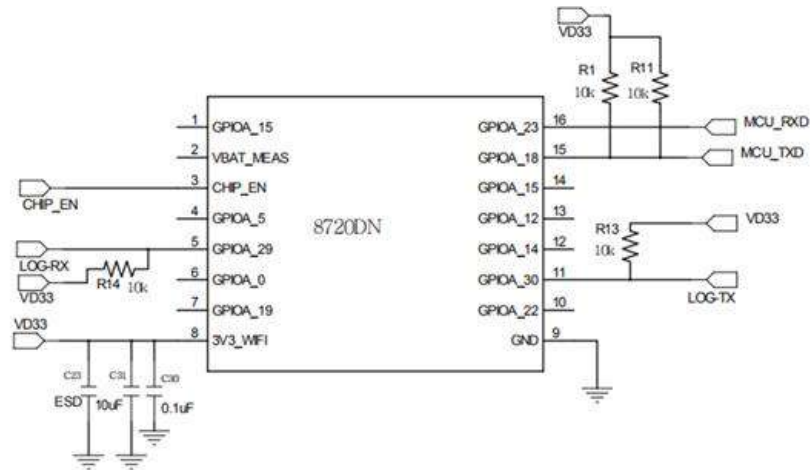


Figure 8 Application Circuit

Note:

- LOG _ TX is the starting control foot in normal operating mode at high level and burning firmware mode at low level. Internal chip default high level.

6.2. Recommend PCB Package

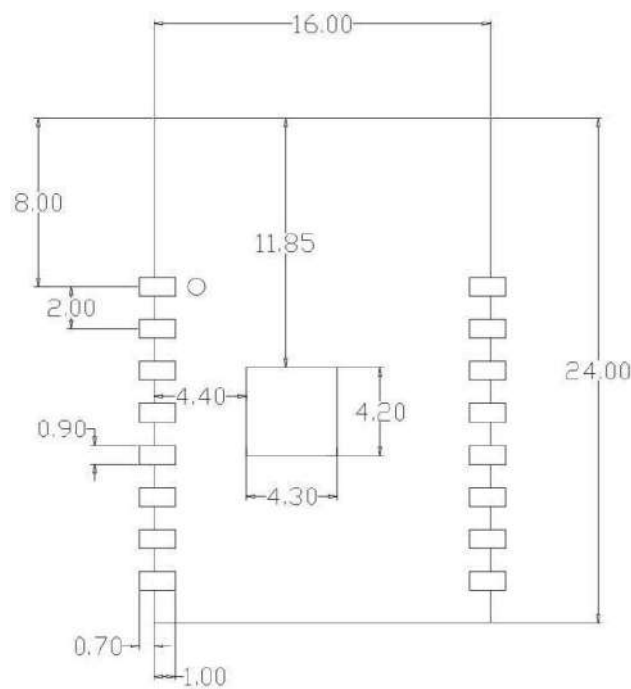


Figure 9 Recommend PCB Package

6.3. Antenna Layout Requirements

- Installation position on the main board, advise for following two ways:
- The module is placed on the edge of the main board, and the antenna area is extended out of the edge of the main board. 2. In order to meet the performance of the on-board antenna, metal parts are prohibited from being placed around the antenna.

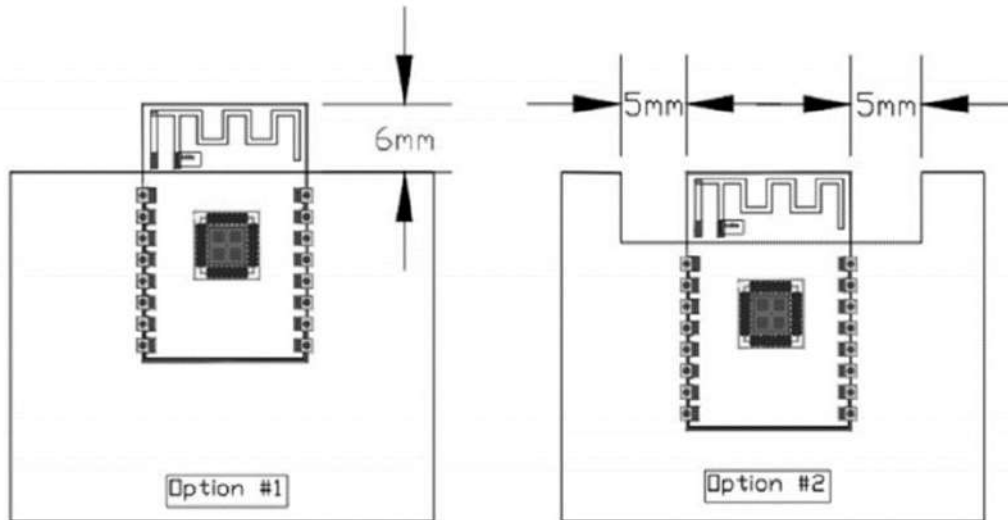


Figure 10 Schematic diagram of Antenna layout

6.4. Power Supply Requirements

- Recommended voltage 5V, Peak: Current over 500mA .
- It is recommended to use the LDO power supply; If DC-DC is used, the ripple is controlled within 30 mV.
- DC-DC power supply circuit is recommended to reserve the position of the dynamic response capacitor, and the output ripple can be optimized when the load change is large.
- Proposed addition of ESD Devices to 5V Power supply Interface.
- For 3.3V application, if the power up slew rate from 1.5V to 3.0V is slower than 15ms, The wide range VCC Flash is needed or add reset IC.
- In the process of power off to power on, if the power off voltage can't be guaranteed to drop below 0.3v and power on again, reset IC should be added.

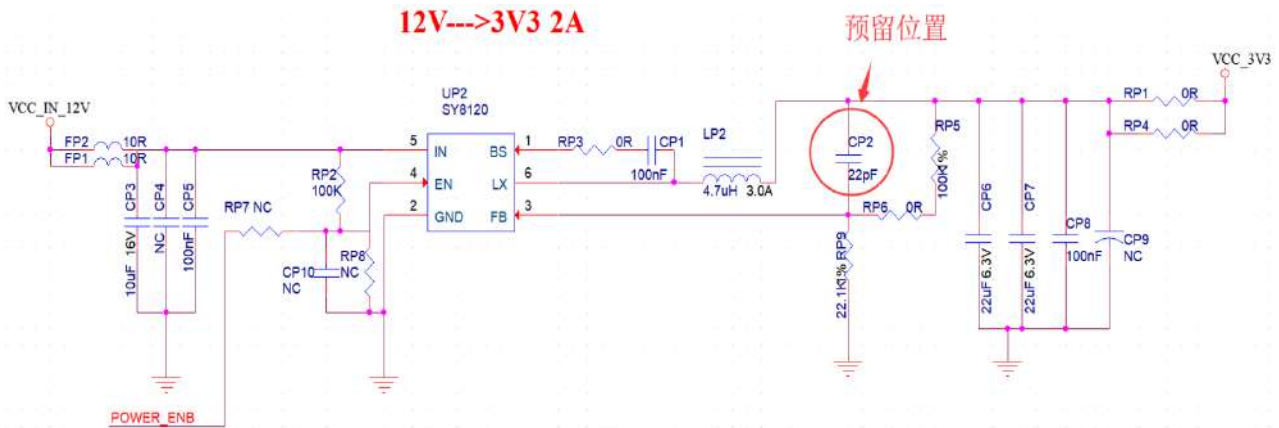


Figure10 DC-DC Buck Circuit

6.5. GPIO

- At the periphery of the module, some GPIO ports are led out, and a resistance of 10-100 ohms can be connected in series on the IO port for use. This suppresses overshoot and is more stable on both sides. Help for both EMI and ESD.
- For the up-and-down drawing of the special io-port, reference will be made to the use description of the specification, which will affect the start-up configuration of the module.
- The IO port of the module is 3.3 v. If the main control does not match the io-level of the module, it is necessary to increase the level conversion circuit.
- If the IO interface is directly connected to the peripheral interface, or the pins and other terminals, it is recommended to reserve the ESD device near the terminal at the IO trace.

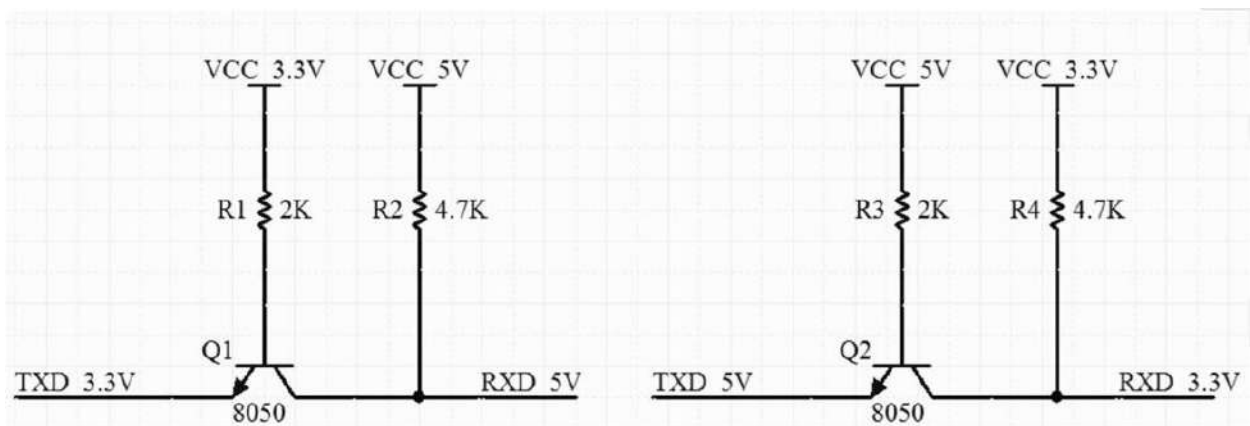


Figure 11 switching circuit

7. ROLLING OF Reflow soldering

Products sealed in a moisture-proof bag shall be stored in a non-condensing atmosphere of <math><40^{\circ}\text{C}</math> / 90% RH.

The moisture sensitivity grade MSL of the module is level 3.

After the vacuum bag is unsealed, it must be used within 168 hours at $25 \pm 5^{\circ}\text{C}$ / 60% RH, otherwise it needs to be baked before the secondary launch.

8. ROLLING OF Reflow soldering

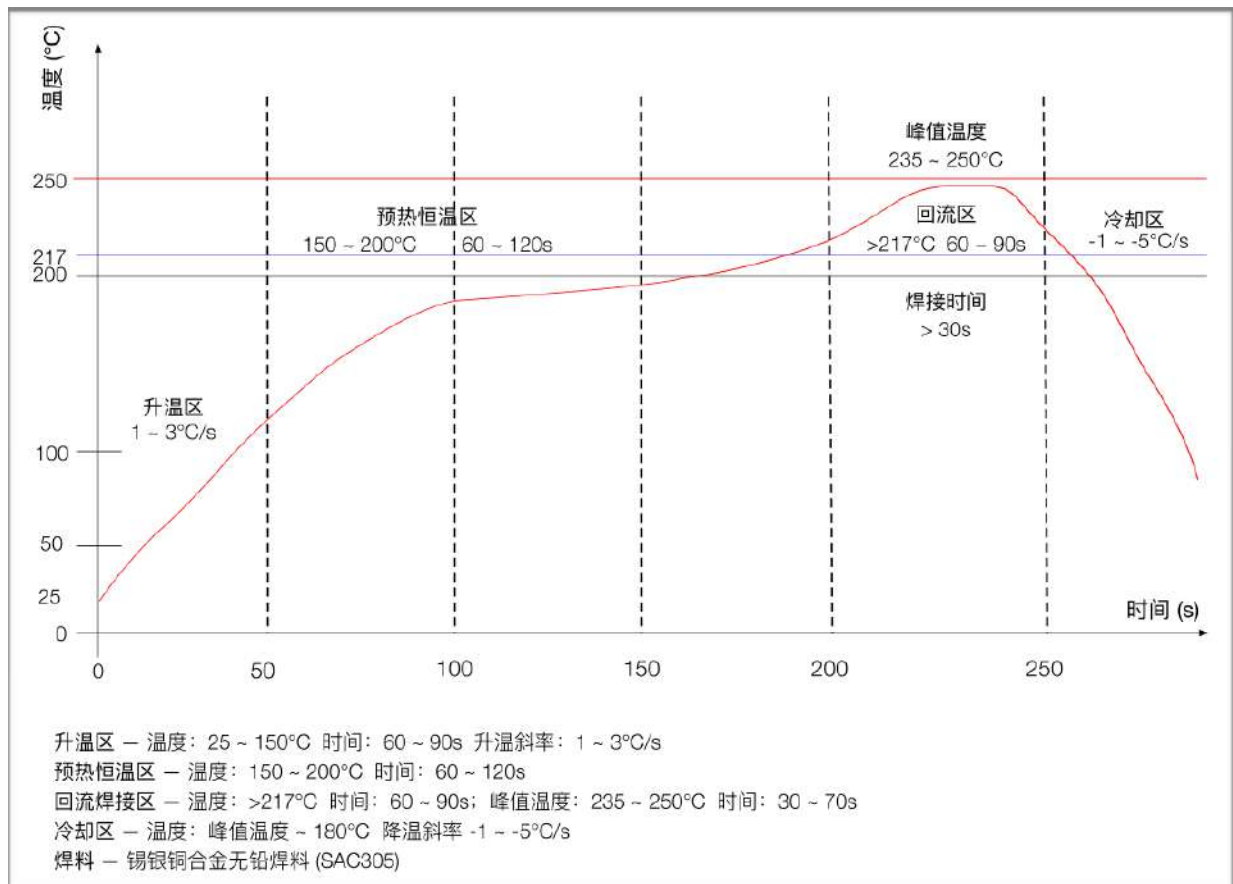


Figure12 ROLLING OF Reflow soldering

9. Package Information

BW16 module is packaged with 800 pcs / disk. As shown in the figure below:



Figure 13 packing ribbon diagram

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[Technical support Email: support@aithinker.com](mailto:support@aithinker.com)

[Domestic business cooperation: sales@aithinker.com](mailto:sales@aithinker.com)

[Overseas business cooperation: overseas@aithinker.com](mailto:overseas@aithinker.com)

Company address: Room 403-405,408-410, Block C, Huafeng Smart Innovation Port, Gushu 2nd Road, Xixiang, Baoan District, Shenzhen.

Tel: 0755-29162996



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